

SMT940-25

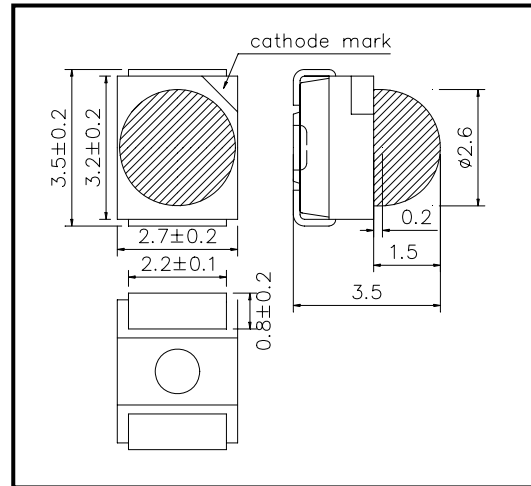
High Performance Infrared TOP LED with Lens

SMT940-25 consists of a AlGaAs LED mounted on the lead frame as TOP LED package with plastic ball lens and is 34mW typical of output power and 26mW/sr of radiant intensity. It emits a spectral band of radiation at 940nm.

♦ Outer dimension (Unit:mm)

♦ Specifications

1) Product Name	TOP IR LED
2) Type No.	SMT940-25
3) Chip	
(1) Chip Material	GaAs
(2) Chip Dimension	400um*400nm
(3) Peak Wavelength	940nm typ.
4) Package	
(1) Lead Frame Die	Silver Plated
(2) Package Resin	PPA Resin
(3) Lens	Epoxy Resin
(4) Diameter	Φ2.6mm



♦ Absolute Maximum Rating

Item	Symbol	Maximum Rated Value	Unit	Ambient Temperature
Power Dissipation	P _D	140	mW	T _a =25°C
Forward Current	I _F	100	mA	T _a =25°C
Pulse Forward Current	I _{FP}	1000	mA	T _a =25°C
Reverse Voltage	V _R	5	V	T _a =25°C
Junction Temperature	T _J	100	°C	
Thermal Resistance	R _{thjp}	260	K/W	
Operating Temperature	T _{OPR}	-20 ~ +80	°C	
Storage Temperature	T _{STG}	-30 ~ +80	°C	
Soldering Temperature	T _{SOL}	255	°C	

‡Pulse Forward Current condition: Duty=1% and Pulse Width=10us.

‡Soldering condition: Soldering condition must be completed within 10 seconds at 255°C

 ♦ Electro-Optical Characteristics [T_a=25°C]

Item	Symbol	Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	V _F	I _F =50mA DC		1.30	1.45	V
		I _F =100mA, t _p =20ms		1.38	1.6	
Reverse Current	I _R	V _R =5V			10	uA
Total Radiated Power	P _O	I _F =50mA DC	12.0	17.0		mW
		I _F =100mA, t _p =20ms		34.0		
Radiant Intensity	I _E	I _F =50mA DC	8	13		mW/sr
		I _F =100mA, t _p =20ms		26		
Peak Wavelength	λ _P	I _F =50mA DC	930	940	955	nm
Half Width	Δλ	I _F =50mA DC		50		nm
Viewing Half Angle	θ _{1/2}	I _F =50mA DC		±23		deg.
Rise Time	t _r	I _F =50mA DC		1000		ns
Fall Time	t _f	I _F =50mA DC		500		ns

‡Total Radiated Power is measured by Photodyne #500

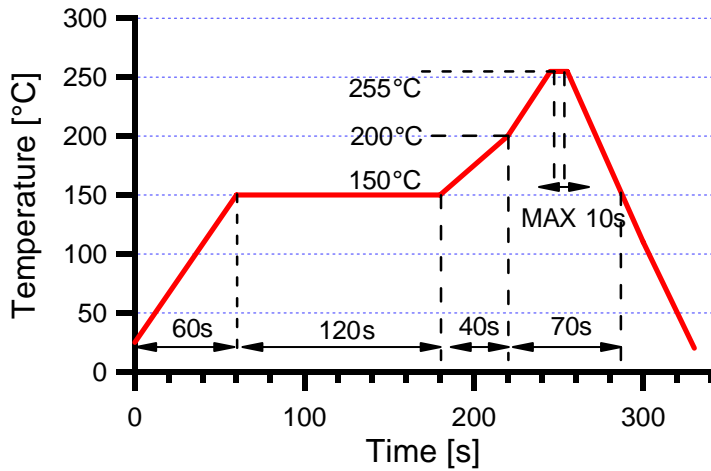
‡Radiant Intensity is measured by Tektronix J-6512.

 USHIO EUROPE B.V. (www.ushio.eu)

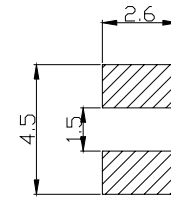
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◆ SMD Application
IR-Reflow Soldering Profile for lead free soldering

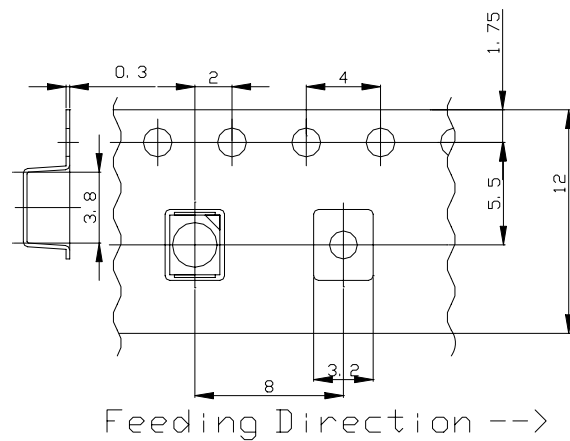
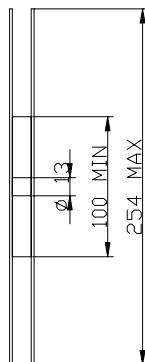
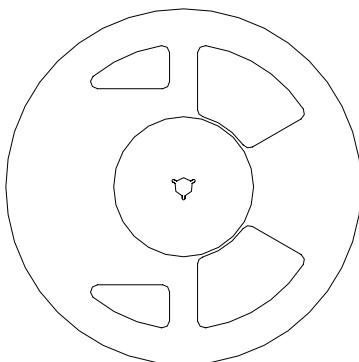


Recommended Land Layout (Unit: mm)



Don't put stress on SMD and a circuit board after soldering.

◆ SMD Packing
Tape and Reel Dimensions (Unit: mm)



◆ Wrapping

Moisture barrier bag aluminum laminated film with a desiccant to keep out the moisture absorption during the transportation and storage.